QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 7.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC}, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC}, T_A = 25°C
- I_{off} Supports Partial-Power-Down-Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

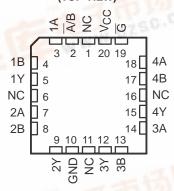
The 'LV157A devices are quadruple 2-line to 1-line data selectors/multiplexers designed for 2-V to 5.5-V V_{CC} operation.

These devices contain inverters and drivers to supply full data selection to the four output gates. A separate strobe (\overline{G}) input is provided. A 4-bit word is selected from one of two sources and is routed to the four outputs. The 'LV157A devices present true data.

SN54LV157A . . . J OR W PACKAGE SN74LV157A . . . D, DB, DGV, NS, OR PW PACKAGE (TOP VIEW)



SN54LV157A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACKA	_{GE} †	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
- EE	2010	Tube of 40	SN74LV157AD	11/4574	
THE WY	SOIC - D	Reel of 2500	SN74LV157ADR	LV157A	
T. Break	SOP – NS	Reel of 2000	SN74LV157ANSR	74LV157A	
4000 1- 0500	SSOP – DB	Reel of 2000	SN74LV157ADBR	LV157A	
-40°C to 85°C		Tube of 90	SN74LV157APW	ニーズでリン	
	TSSOP – PW	Reel of 2000	SN74LV157APWR	LV157A	
		Reel of 250	SN74LV157APWT	MAN MY	
	TVSOP – DGV	Reel of 2000	SN74LV157ADGVR	LV157A	
	CDIP – J	Tube of 25	SNJ54LV157AJ	SNJ54LV157AJ	
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LV157AW	SNJ54LV157AW	
EB	LCCC - FK	Tube of 55	SNJ54LV157AFK	SNJ54LV157AFK	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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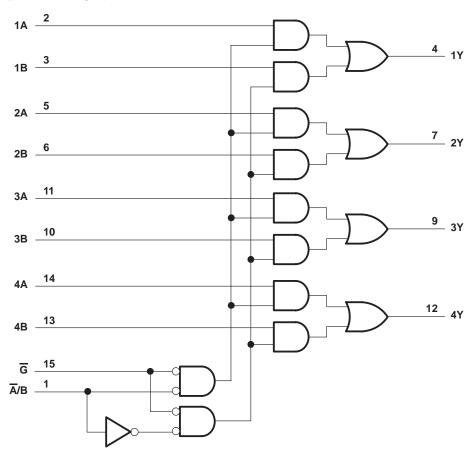
description/ordering information (continued)

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

FUNCTION TABLE

	INPUTS									
_	SELECT	DA	·ΤΑ	OUTPUT						
G	A/B	Α	В	·						
Н	Х	Χ	Χ	L						
L	L	L	X	L						
L	L	Н	X	Н						
L	Н	Х	L	L						
L	Н	Χ	Н	Н						

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, NS, PW, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		
Output voltage range applied in high or low state		
Output voltage range applied in power-off state,		
Input clamp current, I_{IK} ($V_I < 0$)	• ,	
Output clamp current, I _{OK} (V _O < 0)		50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ_{JA} (see Note 3):	D package	73°C/W
	DB package	82°C/W
	DGV package	120°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T _{stq}		65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 4)

			SN54L	V157A	SN74	_V157A		
			MIN	MAX	MIN	MAX	UNIT	
Vcc	Supply voltage		2	5.5	2	5.5	V	
		V _{CC} = 2 V	1.5		1.5			
.,	18.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	$V_{CC} \times 0.7$	7	$V_{CC} \times 0$	7	.,	
V_{IH}	High-level input voltage	V _{CC} = 3 V to 3.6 V	V _{CC} ×0.7	7	$V_{CC} \times 0$.	7	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	V _{CC} ×0.7	7	$V_{CC} \times 0$.	7		
		V _{CC} = 2 V		0.5		0.5		
17	Law law diameterate na	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$,	√CC × 0.3		V _{CC} ×0.3	.,	
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V	,	√CC × 0.3		V _{CC} ×0.3).3	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$,	√CC × 0.3		$V_{CC} \times 0.3$	<u> </u>	
VI	Input voltage		0	5.5	0	5.5	V	
VO	Output voltage		0	VCC	0	Vcc	V	
		V _{CC} = 2 V	S	-50		-50	μΑ	
	LPak Israel and and annual	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	90	-2		-2		
IOH	High-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	Q	-6		-6	mA	
		V _{CC} = 4.5 V to 5.5 V		-12		-12	1	
		V _{CC} = 2 V		50		50	μΑ	
	Law law allow to the state of	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2		
lol	Low-level output current	V _{CC} = 3 V to 3.6 V		6		6	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12		12		
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200	0	200		
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		100	0	100	ns/V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20	0	20		
TA	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEGT COMPITIONS	T	SN54LV157A	SN74LV157A		
PARAMETER	TEST CONDITIONS	vcc	MIN TYP MAX	MIN TYP MAX	UNIT	
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1	V _{CC} -0.1		
V	$I_{OH} = -2 \text{ mA}$	2.3 V	2	2	V	
VOH	$I_{OH} = -6 \text{ mA}$	3 V	2.48	2.48	V	
	I _{OH} = -12 mA	4.5 V	3.8	3.8		
	I _{OL} = 50 μA	2 V to 5.5 V	0.1	0.1		
V	$I_{OL} = 2 \text{ mA}$	2.3 V	0.4	0.4	V	
VOL	I _{OL} = 6 mA	3 V	0.44	0.44	V	
	I _{OL} = 12 mA	4.5 V	0.55	0.55		
ΙĮ	V _I = 5.5 V or GND	0 to 5.5 V	±1	±1	μΑ	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	20	20	μΑ	
l _{off}	V_I or $V_O = 0$ to 5.5 V	0	5	5	μΑ	
Ci	V _I = V _{CC} or GND	3.3 V	1.7	1.7	pF	



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	TO LOAD	T _A = 25°C		SN54LV157A		SN74LV157A				
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	A or B	Υ			7.4*	15.9*	1*	19.5*	1	19.5	
t _{pd}	Ā/B	Y	C _L = 15 pF		7.9*	19.4*	1*	23.5*	1	23.5	ns
· '	G	Υ			7.8*	19.8*	1*	24*	1	24	
	A or B	Υ			9.4	18.8	\$ 1¢	22	1	22	
^t pd	A/B	Υ	C _L = 50 pF		10.8	22.3	\ ? 1	26	1	26	ns
	G	Υ]		9.6	22.7	1	26.5	1	26.5	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD CAPACITANCE	T _A = 25°C		SN54LV157A		SN74LV157A		UNIT	
PARAMETER	(INPUT)	(OUTPUT)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
	A or B	Υ	C _L = 15 pF		5.2*	9.7*	1*	11.5*	1	11.5	
t _{pd}	Ā/B	Υ			5.8*	13.2*	1*	15.5*	1	15.5	ns
, i	G	Υ			5.5*	13.6*	1*	16*	1	16	
	A or B	Υ			6.7	13.2	Q-10	15	1	15	
^t pd	Ā/B	Υ	$C_{L} = 50 \text{ pF}$		7.6	16.7	\Q1	19	1	19	ns
	G	Y]		7	17.1	1	19.5	1	19.5	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	LOAD TA =		. = 25°C		/157A	SN74LV157A		LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	A or B	Υ	C _L = 15 pF		3.6*	6.4*	1*	7.5*	1	7.5	
t _{pd}	Ā/B	Y			4.1*	8.1*	1*	9.5*	1	9.5	ns
·	G	Υ			3.8*	8.6*	1*	10*	1	10	
	A or B	Υ			4.8	8.4	\$ 1¢	9.5	1	9.5	
^t pd	Ā/B	Y	C _L = 50 pF		5.4	10.1	Q1	11.5	1	11.5	ns
	G	Y			5	10.6	1	12	1	12	

 $^{^{\}star}$ On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 5)

	DADAMETED	SN			
	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.3	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic VOL		-0.1	-0.8	V
V _{OH(V)}	Quiet output, minimum dynamic VOH		3.2		V
V _{IH(D)}	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.



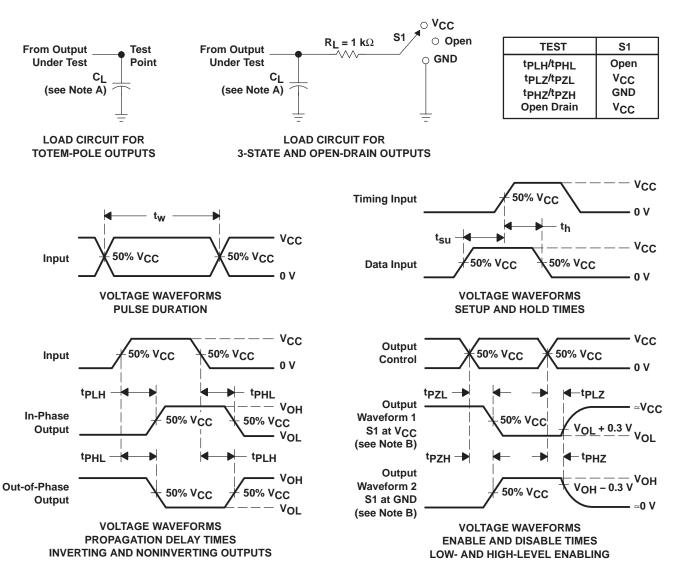
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operating characteristics, $T_A = 25^{\circ}C$

		PARAMETER	TEST COI	VCC	TYP	UNIT	
Г	C .	Dower discination consistence	C. F0 pF	f 40 MH-	3.3 V	12.1	PF
	Cpd	Power dissipation capacitance	$C_L = 50 \text{ pF},$	f = 10 MHz	5 V	13.1	рг

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 3 ns, $t_f \leq$ 3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. t_{PHL} and t_{PLH} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







9-Aug-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV157AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157ADBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157ADBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157ADGVR	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157ADGVRE4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157APW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157APWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157APWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157APWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157APWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV157APWTG4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

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⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

9-Aug-2005

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DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



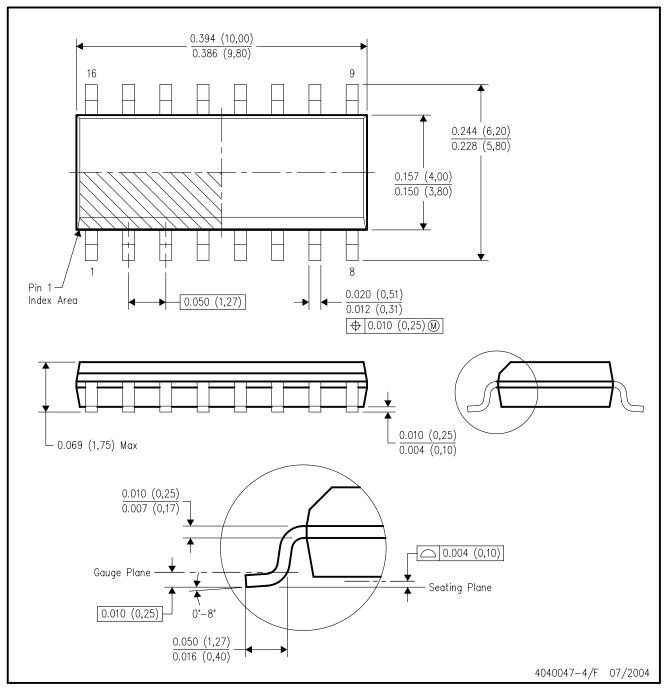
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153 14/16/20/56 Pins – MO-194



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- . All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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